

Panel Bond Tape

Product structure	Designation	Colour	Thickness [mm]
Covering	Polyethylene film	yellow	approx. 0,1
Adhesive covered side	Acrylate pure		approx. 3,0
Carrier	Polyethylene foam	anthracite	
Total thickness			approx. 3,1
Merkmal	Wert	Einheit	Bemerkungen
Shear strength	0,08	N/mm ²	On stainless steel at 23 °C
Peel strength (180°)	1,2	N/mm	
Width	> 6	mm	
Length	25	m	
Processing temperature range	+5 to +40 (ideal: +15 to +35)	°C	
Temperature resistance	-40 bis +100	°C	

Area of application

- Bonding façade panels to a substructure (within the Panel Bond System)
- Securing initial adhesion
- Setting a defined gap of 3 mm

Instructions for bonding façade panels

When bonding façade panels, it is essential to follow all instructions and installation guidelines in the Panel Bond brochure.

Product properties

- High resistance to aging, UV, weathering, solvents, and plasticizers
- High initial tack provides sufficient application reliability immediately after installation. Maximum final strength is achieved after a dwell time of approx. 24 hours.
- Vibration-damping and compensating for different expansion coefficients of the joining partners

General surface preparation and processing instructions

The bonding surfaces must be stable, clean, and free of dust and grease.

If you have any further questions, please contact our technical support team.

Storage

Store in a cool, dry place at +5°C to +25°C.

For further information on handling, please refer to the safety data sheet; this contains important information.

The application instructions in this technical data sheet and our technical advice on application, whether spoken or written, are given to the best of our knowledge but do not constitute either a warranty as to the nature or usability of the products or an independent or dependent promise or warranty declaration of any kind. We recommend to always check the suitability of our products for the intended use. Due to the wide variety of possible applications for each individual product and the unpredictable conditions at the place of processing, we recommend testing the function on the substrates before use.